

## CLAIM AMENDMENTS

1. (Previously Amended) A circuit board comprising:  
a substrate; and  
electrical contacts to mate with a slot connector, the contacts comprising a first set of at least three uniformly spaced contacts to communicate power and a second set of at least three uniformly spaced contacts to communicate signals and not to communicate power, adjacent contacts of the first set being separated by a first distance and adjacent contacts of the second set being separated by a second distance different from the first distance.
2. (Previously Amended) The circuit board of claim 1, wherein the first distance is approximately half of the second distance.
3. (Original) The circuit board of claim 1, wherein the substrate comprises an edge to be inserted into a slot connector housing, and the first and second set of contacts are formed on the edge.
4. (Previously Amended) The circuit board of claim 1, wherein the first distance establishes a pitch of approximately 0.05 inches and the second distance establishes a pitch of approximately 0.10 inches.
5. (Previously Amended) The circuit board of claim 1, further comprising:  
power regulation circuitry mounted on the substrate and in electrical communication with the first set of contacts to regulate voltages provided by the first set of contacts and not regulate any voltages provided by the second set of contacts.
6. (Currently Amended) A circuit board comprising:  
circuitry; and  
a substrate supporting the circuitry and having a contact edge to be inserted into a slot connector housing assembly, the substrate having an edge profile engaged by the connector housing assembly inside the slot connector housing assembly to resist removal of the circuit board from the connector housing assembly.

7. (Cancelled)

8. (Currently Amended) The circuit board of claim ~~7~~ 6, wherein the mechanism comprises at least one of a spring located entirely inside the connector housing assembly and a plastic latch internal to the connector housing assembly.

9. (Previously Amended) The circuit board of claim 6, wherein the profile comprises a notch formed in a straight edge of the substrate, the straight edge being different from the contact edge and being inserted into the slot connector housing to position the edge profile to engage the connector housing assembly.

10. (Previously Amended) The circuit board of claim 9, wherein the straight edge extends in an orthogonal direction to the contact.

11. (Currently Amended) A method comprising:  
supporting circuitry on a substrate to form a circuit board; and  
forming an edge profile in the substrate to engage a slot connector housing assembly inside the slot connector housing assembly to resist removal of the circuit board from the slot connector housing assembly.

12. (Previously Amended) The method of claim 11, further comprising:  
engaging the profile with a mechanism located inside the slot connector housing assembly.

13. (Currently Amended) The method of claim ~~11~~ 12, wherein the mechanism comprises a spring located entirely inside the connector housing assembly.

14. (Original) The method of claim 11, further comprising:  
forming electrical contacts on a first edge of the substrate to circuit board; and  
forming the profile on a second edge of the substrate, the second edge extending in a  
direction substantially orthogonal to a direction along which the first edge extends.

15. (Original) A connector comprising:  
a housing including a slot to receive a circuit board, the housing being formed from a  
material having a thermal conductivity of at least approximately 0.27 W/m·K; and  
electrical contacts secured to the housing to establish electrical communication with  
electrical contact pads of the circuit board.

16. (Original) The connector of claim 15, wherein the material comprises a liquid  
crystal polymer.

17. (Original) The connector of claim 15, wherein the housing comprises fins to  
promote conduction of heat away from the circuit board when the circuit board is inserted into  
the slot.

18. (Original) A method comprising:  
using a material having a thermal conductivity of at least approximately 0.27 W/m·K  
to form a housing for a slot connector, the housing having a slot to receive a circuit board; and  
using the thermal conductivity of the material to conduct heat away from circuitry of  
the circuit board.

19. (Original) The method of claim 18, wherein the material comprises a liquid  
crystal polymer.

20. (Original) The method of claim 18, further comprising:  
forming fins in the housing to conduct heat away from the circuit board when the  
circuit board is inserted into the slot.

21. (Original) A method comprising:  
providing a slot connector to receive a circuit board; and  
forming fins on the slot connector to conduct heat away from circuitry of the circuit board.

22. (Original) The method of claim 21, wherein the slot connector couples the circuit board to another circuit board, the method further comprising:  
providing an edge of the slot connector to mount to said another circuit board; and  
creating clearances between each fin and the edge.

23. (Original) The method of claim 22, wherein each of the clearances is in a range between approximately 1/4 inches and approximately 3/8 inches.

24. (Original) The method of claim 22, further comprising:  
forming the fins out of a liquid crystal polymer.

25. (Currently Amended) A slot connector comprising:  
a housing including a slot to receive a circuit board;  
electrical contacts to establish electrical communication with electrical contacts of the circuit board; and  
a retention mechanism to engage an edge profile of the circuit board inside the slot to secure the circuit board to the slot connector.

26. (Original) The slot connector of claim 25, wherein the retention mechanism is located entirely inside the slot.

27. (Original) The slot connector of claim 25, wherein the retention mechanism comprises a spring.

28. (Currently Amended) A method comprising:  
using a housing to form a slot to receive a circuit board;  
attaching a retention mechanism to the housing to engage an edge profile of the  
circuit board inside the slot to secure the circuit board to the housing.

29. (Original) The slot connector of claim 28, further comprising:  
disposing the retention mechanism entirely inside the slot.

30. (Original) The slot connector of claim 28, wherein the retention mechanism  
comprises at least one of a spring and a plastic latch.

31. (New) A circuit board comprising:  
circuitry; and  
a substrate supporting the circuitry and having a contact edge to be inserted into a slot  
connector housing assembly, the substrate having an edge profile engaged by the connector  
housing assembly to resist removal of the circuit board from the connector housing assembly,  
wherein the profile comprises a notch formed in a straight edge of the substrate, the  
straight edge being different from the contact edge and being inserted into the slot connector  
housing to position the edge profile to engage the connector housing assembly..

32. (New) The circuit board of claim 32, wherein the profile is engaged by a  
mechanism located at least partially inside the slot connector housing assembly.

33. (New) The circuit board of claim 32, wherein the mechanism comprises at  
least one of a spring located entirely inside the connector housing assembly and a plastic latch  
internal to the connector housing assembly.

34. (New) The circuit board of claim 31, wherein the straight edge extends in an  
orthogonal direction to the contact.

35. (New) A method comprising:  
supporting circuitry on a substrate to form a circuit board;  
forming a contact edge on the substrate, the contact edge to be inserted into a slot  
connector housing assembly; and  
forming an edge profile in the substrate to engage the slot connector housing assembly  
to resist removal of the circuit board from the slot connector housing assembly, wherein the  
profile comprises a notch formed in another edge of the substrate.

36. (New) The method of claim 35, further comprising:  
engaging the profile with a mechanism located at least partially inside the slot  
connector housing assembly.

37. (New) The method of claim 35, wherein the mechanism comprises a spring  
located entirely inside the connector housing assembly.

38. (New) The method of claim 35, further comprising:  
forming electrical contacts on a first edge of the substrate to circuit board; and  
forming the profile on a second edge of the substrate, the second edge extending in a  
direction substantially orthogonal to a direction along which the first edge extends.

39. (New) An apparatus comprising:  
a housing to form a slot to receive a circuit board; and  
films thermally coupled to the housing to conduct heat away from circuitry of the  
circuit board.

40. (New) The apparatus of claim 39, wherein the films are formed out of a liquid  
crystal polymer.

41. (New) The apparatus of claim 39, further comprising:  
a retention mechanism located at least partially inside the housing to engage the circuit  
board to resist removal of the circuit board from a housing.